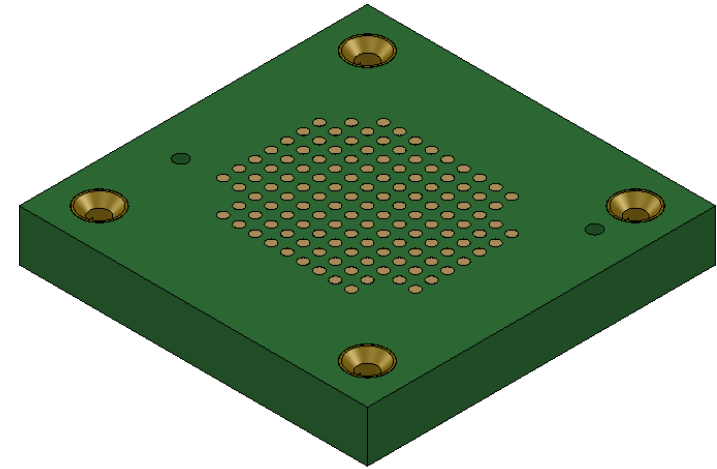
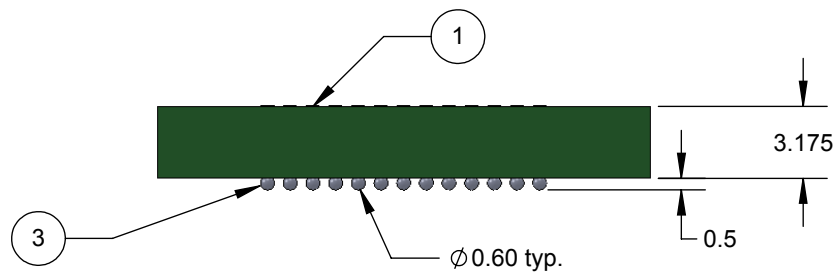


TOP VIEW



SOLDER BALL ALLOY

Sn96.5Ag3.0Cu0.5



FRONT VIEW

| ITEM NO. | PART NUMBER | DESCRIPTION |
|----------|-----------------|--|
| 1 | Substrate | Cu clad substrate |
| 2 | Threaded Insert | #0-80 internal Thread brass insert, Press fit |
| 3 | Solder ball | Solder Ball, 0.024" Dia, See table for alloy composition |



Description: BGA Surface Mount Adapter 13x11 array 1mm pitch. To be used with GHz BGA sockets.

Primary dimension units are millimeters, Secondary dimension units are [inches].

Tolerances: Hole diameters $\pm 0.03\text{mm}$ [± 0.001 "], Pitches (from true position) $\pm 0.025\text{mm}$ [± 0.001 "], substrate thickness tolerance $\pm 10\%$, all other tolerances $\pm 0.13\text{mm}$ [± 0.005 "] unless stated otherwise. Materials and specifications are subject to change without notice.

SF-BGA128G-B-05F Drawing



Ironwood Electronics, Inc.
Tele: (800) 404-0204
www.ironwoodelectronics.com

Material: N/A
Finish: N/A
Weight: 2.23

STATUS: Released

DRAWN BY: S. Huang

FILE: SF-BGA128G-B-05F

SHEET: 1 OF 1

SCALE: 3:1

DATE: 4/16/13

REV. A